

L Number	Hits	Search Text	DB	Time stamp
16	40	134/61,66,78,200,902.ccls. and @pd>20040107	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:47
18	0	((SES adj COMPANY adj LIMITED).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:53
19	1541	((SES).as.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:53
20	2	((SES).as.) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:54
21	3	((SES).as.) and booth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:54
22	10	ohkura.in. and ryoichi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:56
23	1386	ono.in. and yuji.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:57
24	67	(ono.in. and yuji.in.) and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:58
25	2	((ono.in. and yuji.in.) and (semiconductor or wafer or substrate).ti.) and booth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:59
26	7115	yamaguchi.in. and hiroshi.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:58
27	323	(yamaguchi.in. and hiroshi.in.) and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:58
28	3	((yamaguchi.in. and hiroshi.in.) and (semiconductor or wafer or substrate).ti.) and booth	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:59
29	8	takaishi.in. and miyuki.in. and (semiconductor or wafer or substrate).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 10:59

30	2	kamikochi.in. and hideo.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/17 11:00
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